prevent discoloration and corrosion due to a reaction such as oxidation or sulfurization attributable to gas or moisture.

Citation List

Patent Literature

[0006]

Patent Literature 1: JP 2954716 B2

Patent Literature 2: JP 3094000 B2

Patent Literature 3: JP 2004-360066 A

Patent Literature 4: JP 2581021 B2

Summary of Invention

[0006a]

In a first aspect, the present disclosure refers to a laminate comprising

a metallic base material,

a first nickel-containing plating film layer formed on the metallic base material,

a gold plating film layer formed on the first nickel-containing plating film layer,

a second nickel-containing plating film layer formed on the gold plating film layer, and

a nickel fluoride film layer formed on the second nickel-containing plating film layer.

[0006b]

In another aspect, the present disclosure refers to a method for producing a laminate, comprising

a step (A) of forming a first nickel-containing plating film layer on a metallic base material,

a step (B) of forming a gold plating film layer on the first nickel-containing plating film layer,

a step (C) of forming a second nickel-containing plating film layer on the gold plating film layer, and

a step (D) of forming a nickel fluoride film layer on the second nickel-containing plating film layer.

[0006c]

In a further aspect, the present disclosure refers to a constituent member of a semiconductor production device, made up of the laminate disclosed herein.

Technical Problem

[0007]

As a result of a study by the present inventors, the methods of forming a fluorinated passive film of nickel on a nickel-phosphorus alloy plating surface as disclosed in Patent Literature 1 to Patent Literature 3 were found to involve insufficient hydrochloric acid corrosion resistance in some cases, due to the occurrence of corrosion starting

from pinholes in nickel-phosphorus alloy plating. The method disclosed in Patent Literature 4 had a problem that remarkably increased corrosion resistance cannot be expected since the outermost surface layer is alloy plating.